



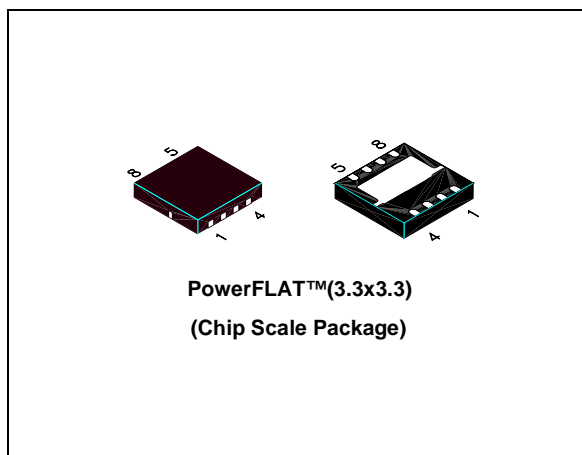
STL8NH3LL

N-channel 30V - 0.012Ω - 8A - PowerFLAT™
Ultra low gate charge STripFET™ Power MOSFET

General features

Type	V _{DSS}	R _{DS(on)}	I _D
STL8NH3LL	30V	<0.015Ω	8A ⁽¹⁾

- Improved die-to-footprint ratio
- Very low profile package (1mm max)
- Very low thermal resistance
- Very low gate charge
- Low threshold device
- In compliance with the 2002/95/EC European directive



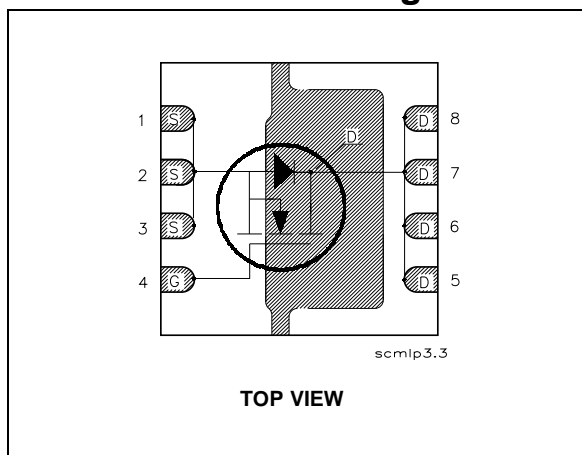
Description

This application specific Power MOSFET is the latest generation of STMicroelectronics unique “STripFET™” technology. The resulting transistor is optimized for low on-resistance and minimal gate charge. The Chip-scaled PowerFLAT™ package allows a significant board space saving, still boosting the performance.

Applications

- Switching application

Internal schematic diagram



Order codes

Sales Type	Marking	Package	Packaging
STL8NH3LL	8NH3L	PowerFLAT™ (3.3 x 3.3)	Tape & reel

Contents:

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves)	6
3	Test circuit	8
4	Package mechanical data	9
5	Revision history	11

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS} = 0$)	30	V
V_{GS}	Gate-Source Voltage	± 18	V
$I_D^{(1)}$	Drain Current (continuous) at $T_C = 25^\circ\text{C}$	8	A
$I_D^{(1)}$	Drain Current (continuous) at $T_C = 100^\circ\text{C}$	5	A
$I_{DM}^{(2)}$	Drain Current (pulsed)	32	A
$P_{TOT}^{(3)}$	Total Dissipation at $T_C = 25^\circ\text{C}$	50	W
$P_{TOT}^{(1)}$	Total Dissipation at $T_C = 25^\circ\text{C}$	2	W
	Derating Factor	0.4	W/ $^\circ\text{C}$
T_J T_{stg}	Operating Junction Temperature Storage Temperature	-55 to 150	$^\circ\text{C}$

1. The value is rated according $R_{thj-pcb}$
2. Pulse width limited by safe operating area.
3. The value is rated according R_{thj-c}

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case (Drain)	2.5	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	42.8	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(2)}$	Thermal resistance junction-pcb	63.5	$^\circ\text{C}/\text{W}$

1. When mounted on FR-4 board of 1inch², 2oz Cu, $t < 10\text{sec}$
2. Steady state

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu A, V_{GS} = 0$	30			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating},$ $V_{DS} = \text{MaxRating} @ 125^{\circ}C$			1 10	μA μA
I_{GSS}	Gate Body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 18V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1		2.5	V
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS} = 10V, I_D = 4A$ $V_{GS} = 4.5V, I_D = 4A$		0.012 0.0135	0.015 0.017	Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward Transconductance	$V_{DS} = 15V, I_D = 4A$		30		S
C_{iss}	Input Capacitance	$V_{DS} = 25V, f = 1 \text{ MHz}, V_{GS} = 0$		965		pF
C_{oss}	Output Capacitance			285		pF
C_{rss}	Reverse Transfer Capacitance			38		pF
Q_g	Total Gate Charge	$V_{DD} = 15V, I_D = 8A$		9	12	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 4.5V$		3.7		nC
Q_{gd}	Gate-Drain Charge	(see Figure 7)		3		nC
R_G	Gate Input Resistance	$f = 1 \text{ MHz}$ Gate DC Bias = 0 Test Signal Level = 20mV Open Drain	0.5	1.5	2.5	Ω

1. Pulsed: pulse duration=300 μs , duty cycle 1.5%

Table 5. Switching times

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=15V, I_D=4A,$ $R_G=4.7\Omega, V_{GS}=4.5V$ (see Figure 13)		15		ns
t_r	Rise Time			32		ns
$t_{d(off)}$	Turn-off Delay Time			18		ns
t_f	Fall Time			8.5		ns

Table 6. Source drain diode

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain Current				8	A
$I_{SDM}^{(1)}$	Source-drain Current (pulsed)				32	A
$V_{SD}^{(2)}$	Forward on Voltage	$I_{SD}=8A, V_{GS}=0$			1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD}=8A,$ $di/dt = 100A/\mu s,$ $V_{DD}=20V, T_j=150^\circ C$ (see Figure 15)		24		ns
Q_{rr}	Reverse Recovery Charge			17.4		nC
I_{RRM}	Reverse Recovery Current			1.45		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

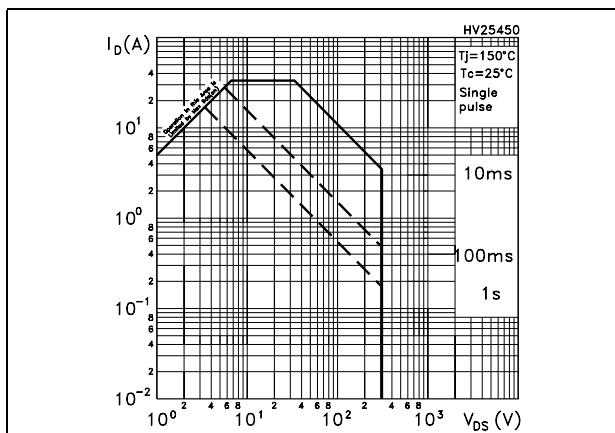


Figure 2. Thermal impedance

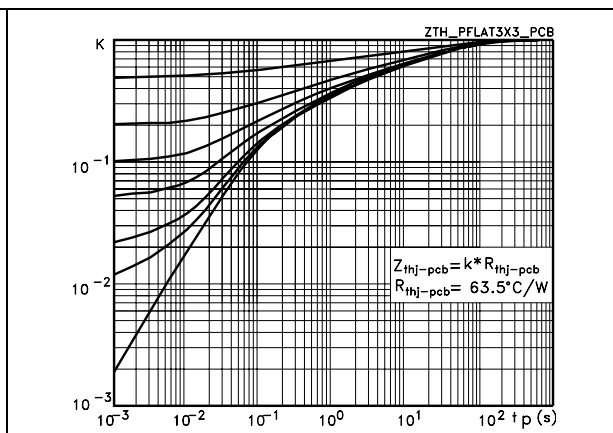


Figure 3. Output characteristics

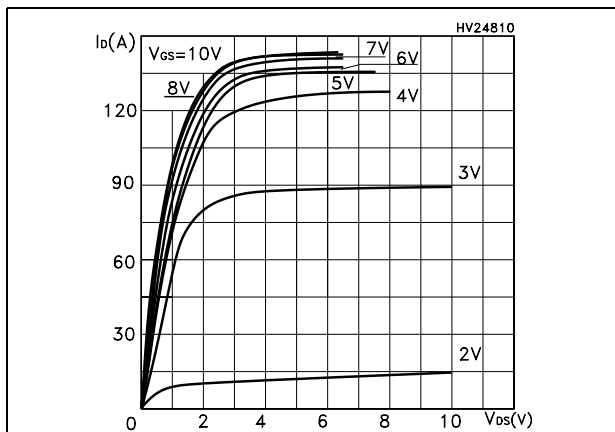


Figure 4. Transfer characteristics

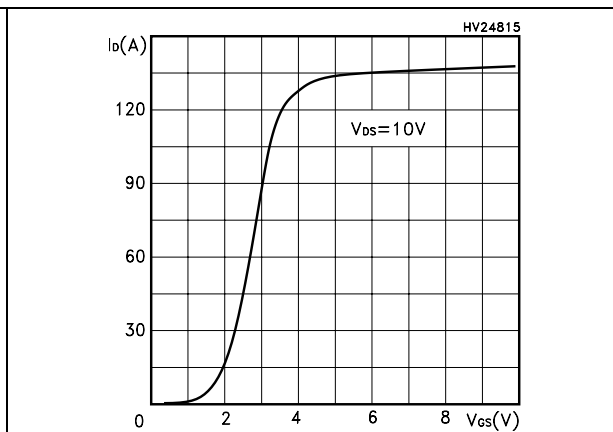


Figure 5. Transconductance

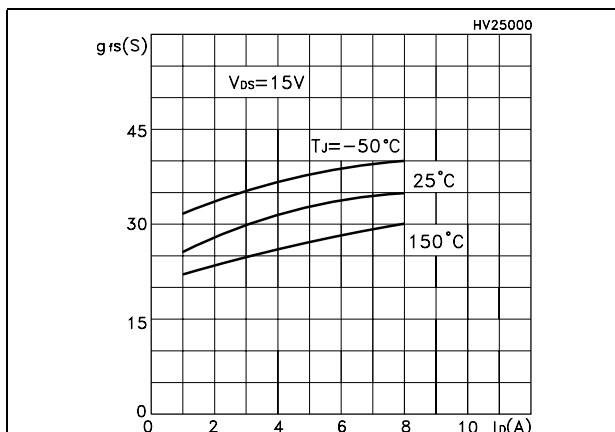


Figure 6. Static drain-source on resistance

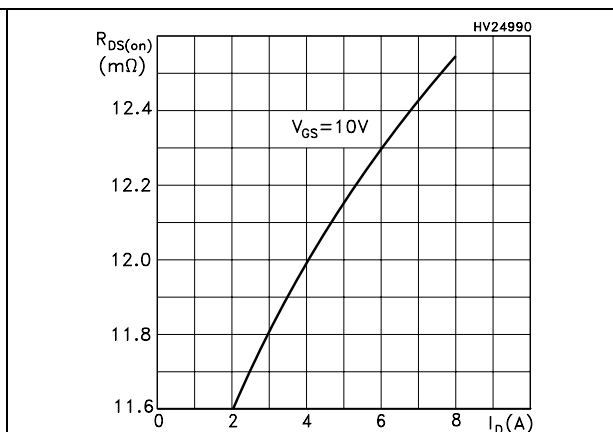


Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

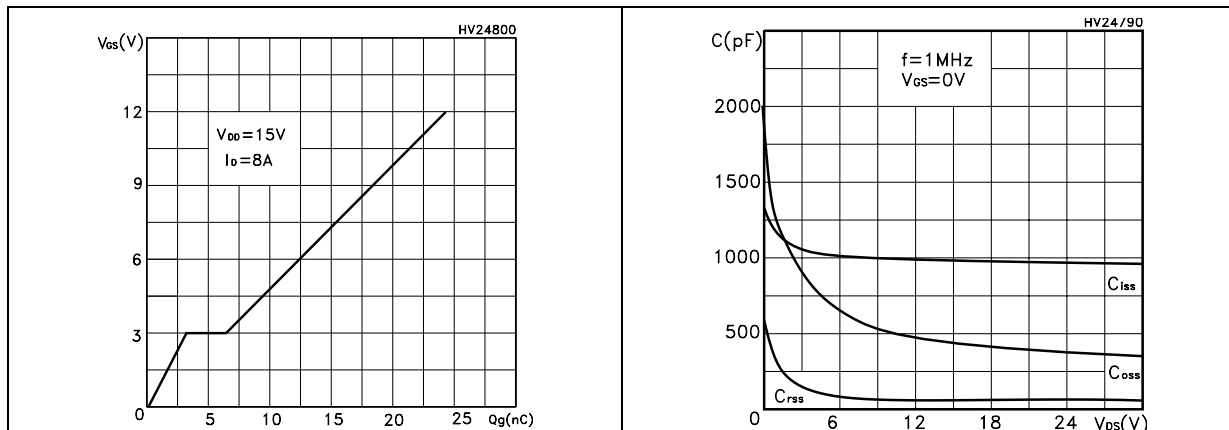


Figure 9. Normalized gate threshold voltage vs temperature Figure 10. Normalized on resistance vs temperature

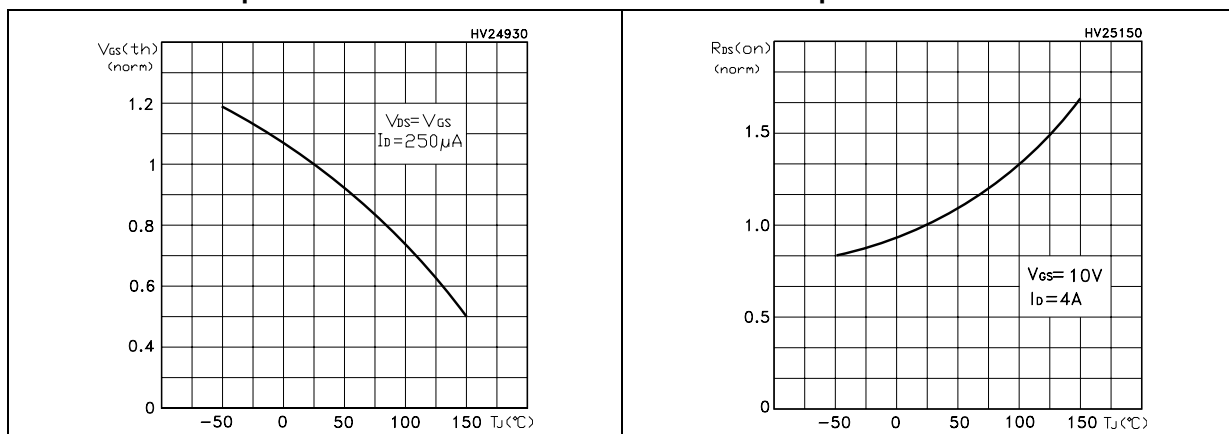
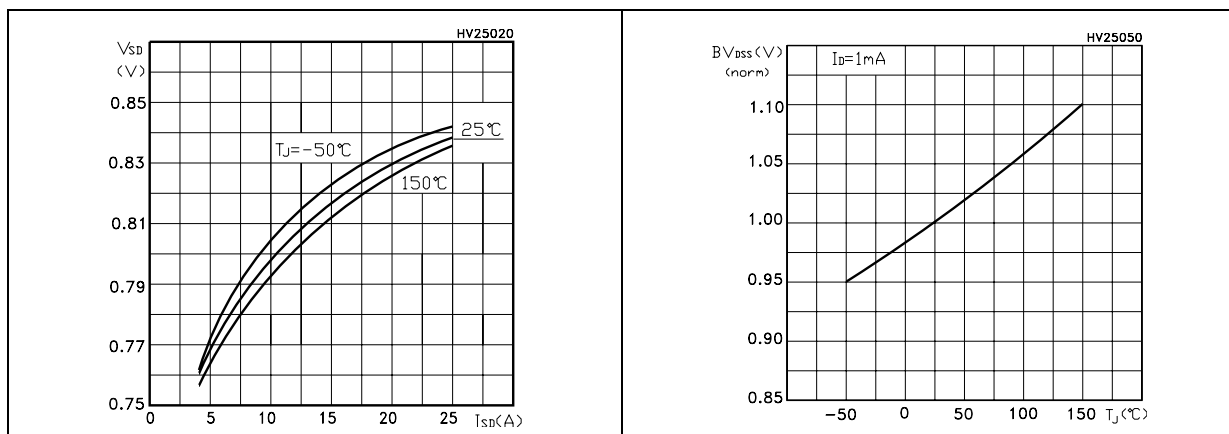


Figure 11. Source-drain diode forward characteristics Figure 12. Normalized B_{VDSS} vs temperature



3 Test circuit

Figure 13. Switching times test circuit for resistive load

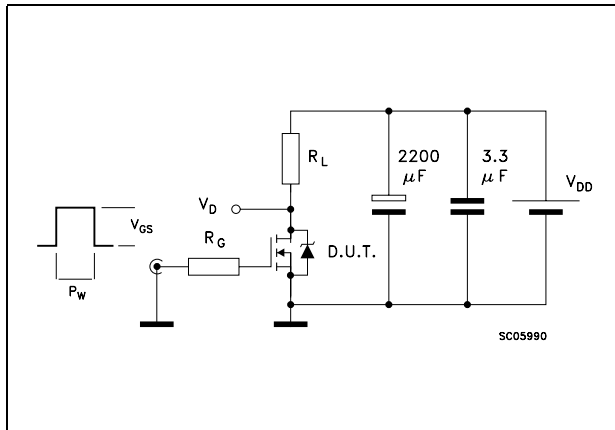


Figure 14. Gate charge test circuit

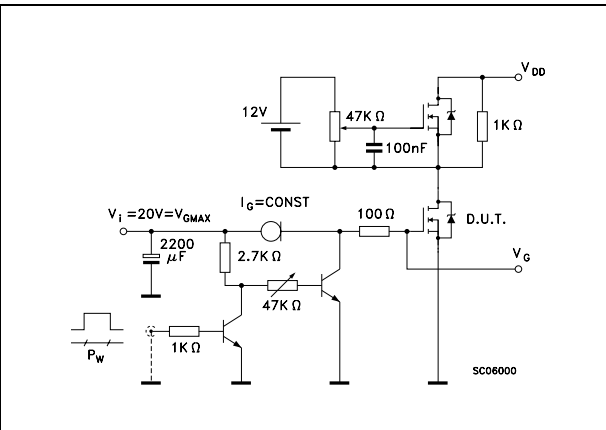


Figure 15. Test circuit for inductive load switching and diode recovery times

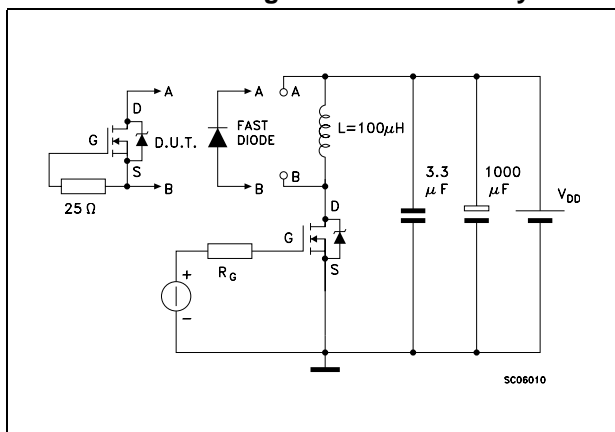


Figure 16. Unclamped inductive load test circuit

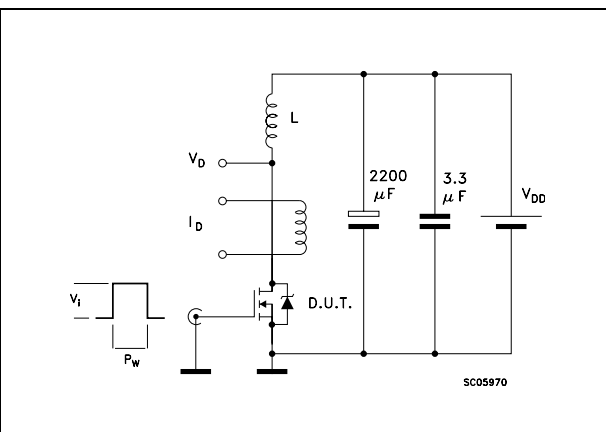


Figure 17. Unclamped inductive waveform

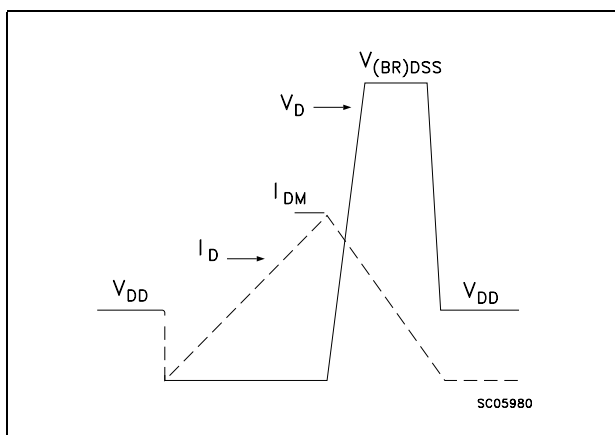
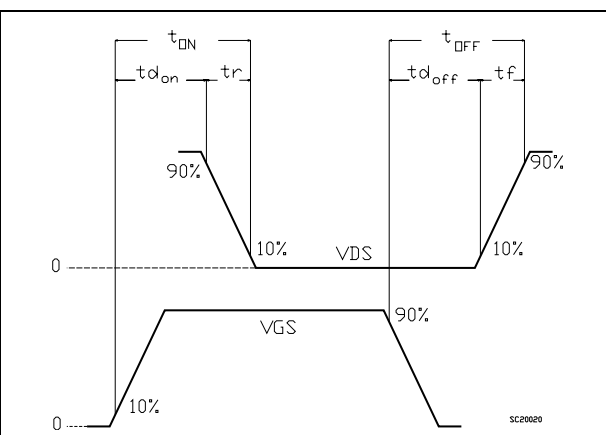


Figure 18. Switching time waveform

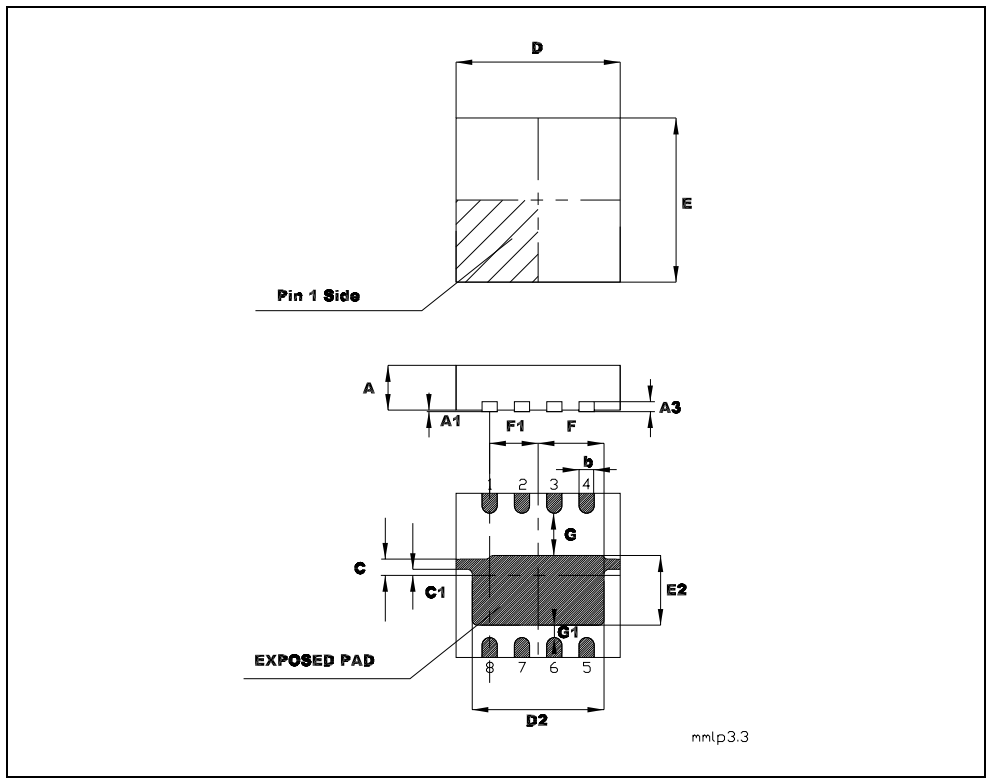


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

PowerFLAT™ (3.3 x 3.3) MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	0.80	0.90	1.00	0.031	0.035	0.039
A1		0.02	0.05		0.0007	0.0019
A3		0.20			0.0007	
b	0.23	0.30	0.38	0.009	0.011	0.015
C		0.328			0.012	
C1		0.12			0.004	
D		3.30			0.13	
D2	2.50	2.65	2.75	0.098	0.104	0.108
E		3.30			0.13	
E2	1.25	1.40	1.50	0.049	0.055	0.059
F		1.325			0.052	
F1		0.975			0.038	
G		0.850			0.033	
G1		0.250			0.009	



5 Revision history

Table 7. Revision history

Date	Revision	Changes
21-Jul-2004	1	First Release
05-Oct-2004	2	Values Changed
19-Oct-2004	3	New value inserted
22-Nov-2004	4	Document updated
21-Feb-2005	5	Final version
18-Apr-2005	6	Modified Figure 3 , Figure 5. , Figure 8. , Figure 9.
14-Mar-2006	7	New template

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